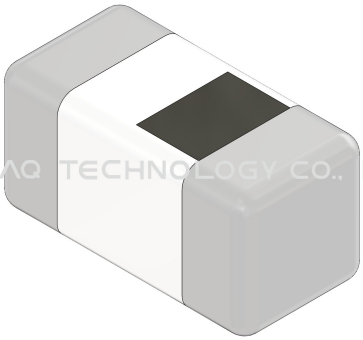
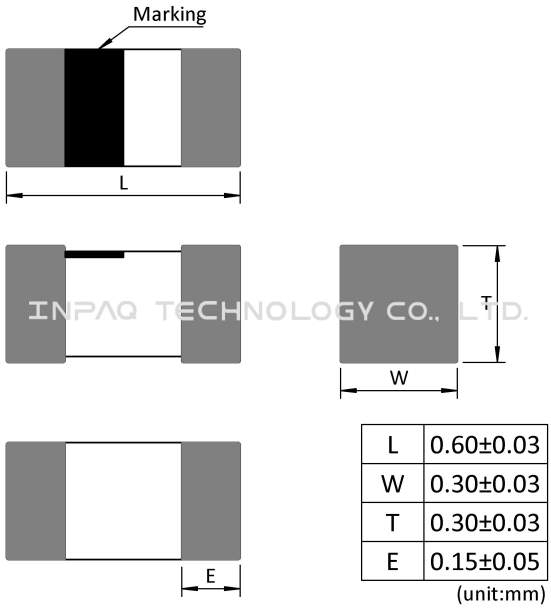
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MCI0603TM3N6_HBP

一般用 ROHS HF

外觀&形狀





L	0.60±0.03
W	0.30±0.03
T	0.30±0.03
E	0.15±0.05

(unit:mm)

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規格

長(公釐)	0.6±0.03
寬(公釐)	0.3±0.03
高(公釐)	0.3±0.03
尺寸代碼 英吋(公釐)	0201(0603)
感值(nH)	3.6
公差	B(±0.1nH), C(±0.2nH), S(±0.3nH)
測試頻率(MHz)	500
最大值直流阻抗(Ω)	0.3
最大溫升電流(mA)	400
最小值品質因素	14
最小值自我諧振頻率(MHz)	6000
操作溫度℃	-55~+125

PASSIVE SYSTEM ALLIANCE
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特點

●Particular ceramic material and coil structure provide high frequency application range up to 10GHz.

●Small size and low profile.

●Available in various sizes.

●Excellent solderability and heat resistance.

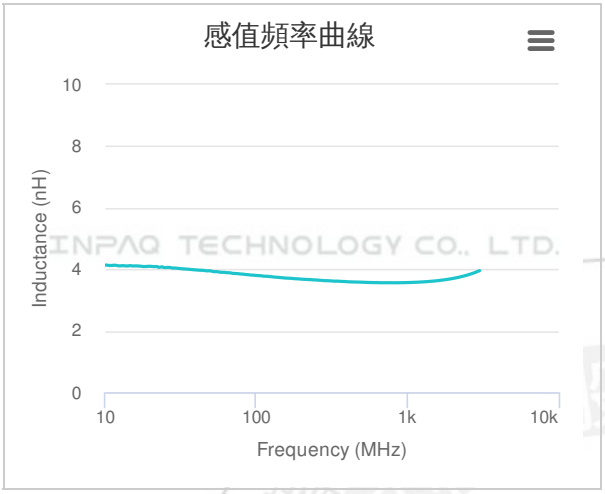
包裝訊息

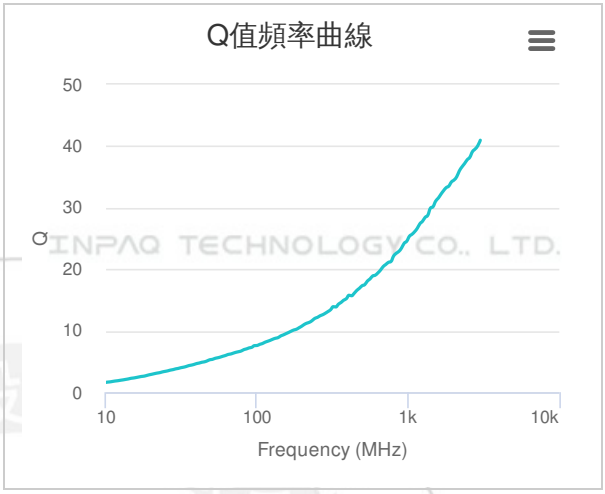
包裝尺寸(Inch)	包裝類型	標準包裝(PCS)	單重(gram)	濕敏等級
7	Paper type	15000	0.000183	1

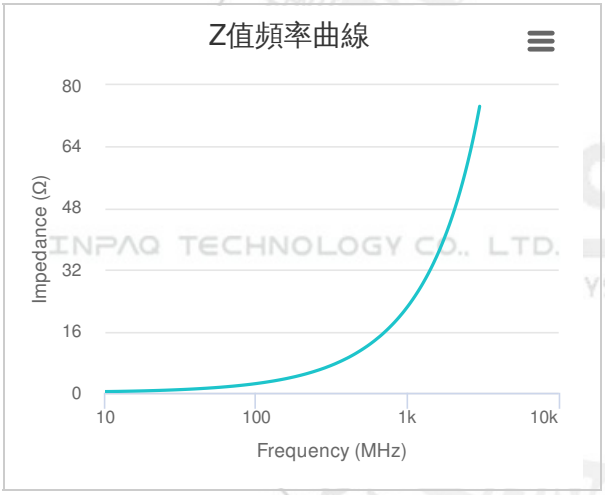
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特性曲線







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